In The Claims

Please cancel claims 1-8.

Please add new claims 9-28 as follows:

9. (New) A circuit device, comprising:

a dielectric substrate, the dielectric substrate having a first area and a second area;

at least one conductive pattern formed in the first area; and

at least one earthed conductor formed on the second area wherein the position of each earthed conductor is changeable on the second area to achieve a desired frequency characteristic.

10. (New) The circuit device according to claim 9, wherein the area of the earthed conductor is changeable on the second area to achieve a desired frequency characteristic.

11. (New) The circuit device according to claim 9, wherein the first layer is an inside layer of the dielectric substrate.

12. (New) The circuit device according to claim 9, wherein the second layer is an outside of the dielectric substrate.

13. (New) The circuit device according to claim 9, wherein each earthed conductor are positioned in a spaced relation on the second area.

14. (New) The circuit device according to claim 13, wherein the spaced relation is lattice shaped.

15. (New) A printed board, comprising:

a circuit device positioned on the circuit board;

a dielectric substrate, the dielectric substrate having a first area and a second area;

a conductive pattern formed in the first area;

an earthed conductor formed on the second area wherein the position of each earthed conductor is changeable on the second area to achieve a desired frequency characteristic; and

a mounted circuit part having a signal processing circuit for processing the desired frequency characteristic signal.

16. (New) The circuit device according to claim 15, wherein the area of the earthed conductor is changeable on the second area to achieve a desired frequency characteristic.

17. (New) The circuit device according to claim 15, wherein the first layer is an inside layer of the dielectric substrate.

18. (New) The circuit device according to claim 15, wherein the second layer is an outside of the dielectric substrate.

19. (New) The circuit device according to claim 15, wherein each earthed conductor are positioned in a spaced relation on the second area.

20. (New) The circuit device according to claim 19, wherein the spaced relation is lattice shaped.

21. (New) A method of forming a circuit device, comprising:

forming a conductive pattern within a dielectric substrate;

forming an earthed conductive pattern on the outside of the dielectric substrate; and

adjusting the frequency characteristic of the circuit device by changing the area and position of the earthed conductor pattern which changes the distribution of the electromagnetic field between the conductive pattern and the earthed conductor pattern.

22. (New) The method of forming a circuit device according to claim 21, further comprising connecting the earthed conductor pattern by via holes.

23. (New) A method of forming a circuit device according to claim 21, further comprising shortening a length of a pile of the conductive pattern by expanding the width of the pattern of the conductive pattern.

24. (New) A method of forming a circuit device according to claim 21, further comprising forming the earthed conductive pattern in a lattice shape, the lattice shape having open areas without the earthed conductor pattern.

25. (New) A method of forming a circuit device according to claim 24, further comprising narrowing the frequency characteristic by forming conductive parts on the open areas.

26. (New) A method of forming a circuit device according to claim 21, further comprising widening the frequency characteristic by removing portions of the earthed conductor pattern.

27. (New) A method of forming a circuit device according to claim 21, wherein the conductive pattern is formed inside the dielectric substrate.

28. (New) A method of forming a circuit device according to claim 21, wherein the earthed conductor pattern is formed on the outside of the substrate.

In The Specification

Please replace paragraph 1 on page 1 between lines 6-12 with the following substituted paragraph:

--The invention relates to a circuit device and a printed board. More particularly, the invention relates to forming a conductive pattern in an inside layer in the dielectric substrate and an earthed conductor in outside layer in the dielectric substrate. Moreover this invention enables